

HD74LS73A

Dual J-K Flip-Flops (with Clear)

REJ03D0414-0300 Rev.3.00 Jul.22.2005

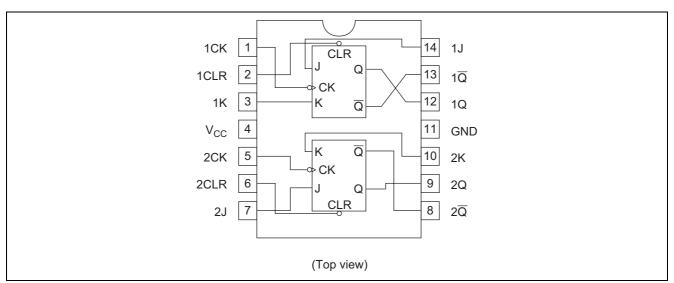
Features

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS73AP	DILP-14 pin	PRDP0014AB-B (DP-14AV)	Р	_
HD74LS73ARPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Function Table

	Inp	Outputs				
Clear	Clock	J	K	Q	Q	
L	X	X	X	L	Н	
Н	\	L	L	Q_0	\overline{Q}_0	
Н	\	Н	L	Н	L	
Н	\	L	Н	L	Н	
Н	<u> </u>	Н	Н	Toggle		
Н	Н	X	X	Qo	\overline{Q}_O	

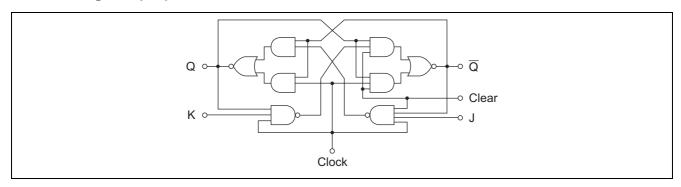
H; high level, L; low level, X; irrelevant, ↓; transition from high to low level,

Q₀; level of Q before the indicated steady-state input conditions were established.

 $[\]overline{Q}_0$; complement of \overline{Q}_0 or level of Q before the indicated steady-state input conditions were established.

Toggle; each output changes to the complement of its previous level on each active transition indicated by \downarrow .

Block Diagram (1/2)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	Vcc	7	V
Input voltage	V _{IN}	7	V
Power dissipation	P _T	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Тур	Max	Unit	
Supply voltage	Vcc	4.75	5.00	5.25	V	
Output ourront	Іон	_	_	-400	μΑ	
Output current	I _{OL}	_	_	8	mA	
Operating temperature	Topr	-20	25	75	°C	
Clock frequency	f _{clock}	0	_	30	MHz	
Pulse width	tw (Clock High)	20	_	_	no	
Fulse width	t _w (Clear Low)	25	_	_	ns	
Setup time	t _{su ("H" Data)}	20↓	_	_	no	
	t _{su ("L" Data)}	20↓	_	_	ns	
Hold time	t _h	0↓	_	_	ns	

Note: \downarrow ; The arrow indicates the falling edge.

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$

Item		Symbol	min.	typ.*	max.	Unit	Condition		
Input voltage		V_{IH}	2.0			V			
		V_{IL}	_		0.8	V			
		V _{OH}	2.7	-		٧	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V},$ $I_{OH} = -400 \mu A$		
Output voltage			_		0.5		$I_{OL} = 8 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V},$		
		V _{OL}	_	_	0.4	V	$I_{OL} = 4 \text{ mA}$ $V_{IL} = 0.8 \text{ V}$		
	J, K		_	_	20				
	Clear	I _{IH}	_	_	60	μΑ	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$		
	Clock		_	_	80				
	J, K		_	_	-0.4	mA			
Input current	Clear	I _{IL}	_	_	-0.8		$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$		
	Clock		_	_	-0.8				
	J, K		_	_	0.1				
	Clear	I _I	_	_	0.3	mA	$V_{CC} = 5.25 \text{ V}, V_I = 7 \text{ V}$		
	Clock		_	_	0.4				
Short-circuit output current		Ios	-20	_	-100	mA	V _{CC} = 5.25 V		
Supply current**		Icc	_	4	6	mA	V _{CC} = 5.25 V		
Input clamp voltage	9	V _{IK}	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$		

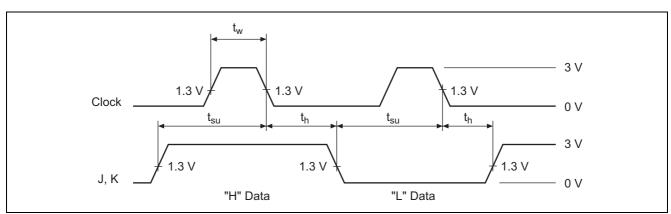
Notes: * $V_{CC} = 5 \text{ V}$, $Ta = 25^{\circ}C$

Switching Characteristics

 $(V_{CC} = 5 \text{ V}, \text{Ta} = 25^{\circ}\text{C})$

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Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition	
Maximum clock frequency	f _{max}			30	45	_	MHz		
Propagation delay time	Propagation delay time	t _{PLH}	Clear	Q, \overline{Q}	_	15	20	ns	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$
i Topagation delay time	t _{PHL}	Clock	Q, Q	_	15	20	ns		

Timing Definition

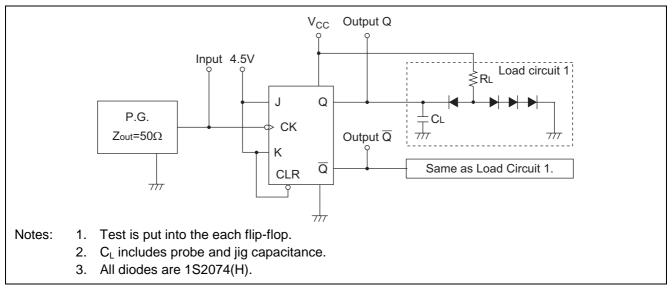


^{**} With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At time of measurement, the clock input is founded.

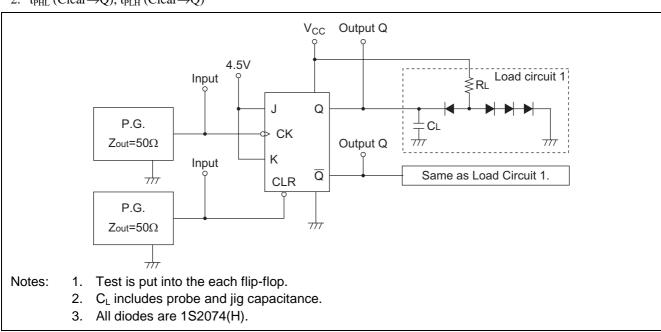
Testing Method

Test Circuit

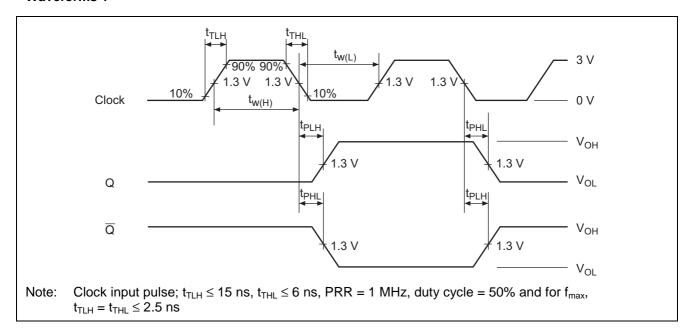
1. f_{max} , t_{PLH} , t_{PHL} , (Clock \rightarrow Q, \overline{Q})



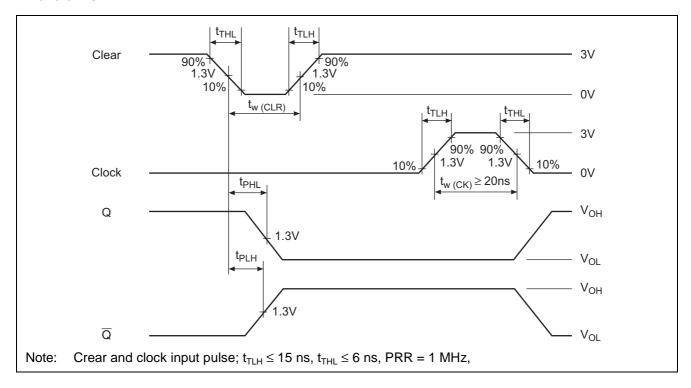
2. t_{PHL} (Clear \rightarrow Q), t_{PLH} (Clear \rightarrow \overline{Q})



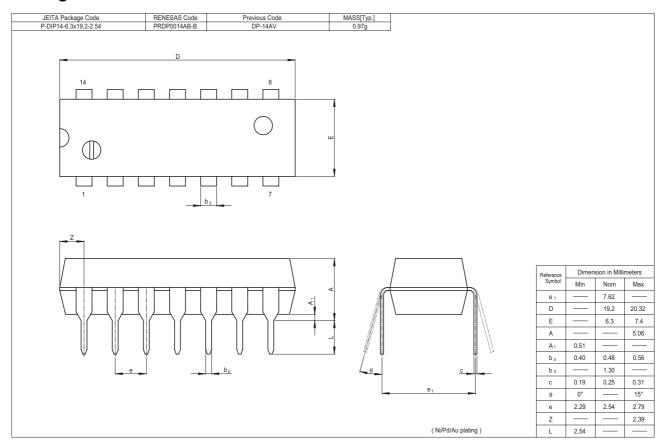
Waveforms 1

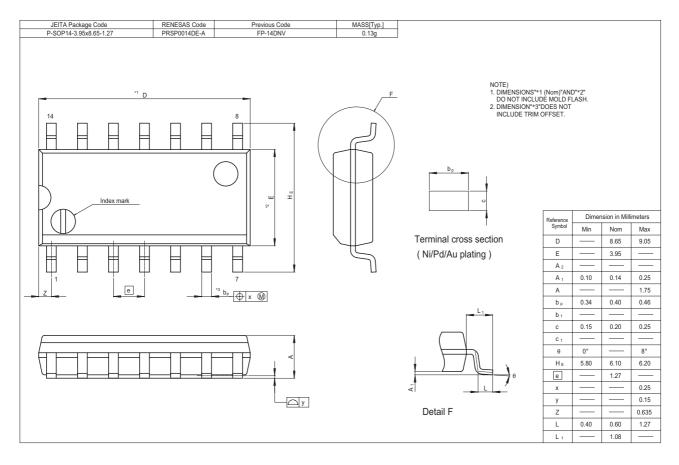


Waveforms 2



Package Dimensions





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